



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1709-04

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at UTL, Thailand.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (UTL, Thailand)	Alternate Assembly (ASECL, Taiwan)
Die Attach	8600	EN4900G
Bond Wire	Copper Wire	Copper Wire
Mold Compound	G700LTD	G700LA



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Qualification Information and Qualification Data:

Affected Packages: VFQFPN-28

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: VFQFPN-36

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Ball Shear Test	JESD22-B116	0/5	0/5	0/5
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
X Ray	IDT Spec. MAC- 3012	0/45	0/45	0/45
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260 °C	0/25	0/25	0/25

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



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Part Number	Part Number	Part Number	Part Number
F1451NKG1	F1456NKG1	F1455NKG18	F1451NKGK
F1456NKGK	F1455NKGK8	F1455NKG1	F1451NKG18
F1456NKG18	F1455NKGK	F1451NKGK8	F1456NKGK8